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IC MOUNTING METHOD

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IC MOUNTING METHOD

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ABSTRACT

PURPOSE: To provide an IC mounting method by which stable electrical connection can be obtained by eliminating the problem of defective connection caused by the thrusting-up force of a thermally expanded IC chip when a liquid sealing resin filling up the gap between a circuit board and the IC chip is heated at the time of connecting the IC chip used for electronic equipment with the circuit board, such as a liquid crystal panel, etc.

CONSTITUTION: After a conductive bonding agent 4 is applied to the top sections of bumps (projecting contact) 3 formed on electrodes pads 2 on an IC chip 1 and connecting the chip 1 to terminal electrodes 6 on a circuit board 5 by positioning and press-contacting the chip 1 to and upon the electrodes 6 and hardening the bonding agent 4 by heating, the gap between the IC chip 1 and circuit board 5 is filled up with a sealing resin 7 and the resin 7 is hardened by heating while the chip 1 is pressed against the board 5 with a load stronger than the thrusting-up force of the thermally expanded chip 1 at the time of heating the resin 7 by using a pressurizing jig 8. Therefore, since the resin 7 is hardened while a load or pressure stronger than the thrusting-up force of the chip is applied, the occurrence of defective connection caused by the thrusting-up force of the chip 1 can be prevented.